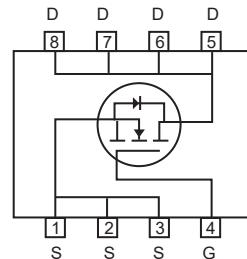
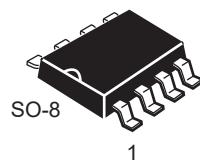


## Single N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 100V, 11.7A,  $R_{DS(ON)} = 12m\Omega$  @ $V_{GS} = 10V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handing capability.
- RoHS compliant.
- Surface mount Package.



### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ C$ unless otherwise noted

Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	11.7	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	46.8	A
Maximum Power Dissipation	$P_D$	3.13	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	40	$^\circ C/W$

**CEM1210A****Electrical Characteristics**  $T_A = 25^\circ\text{C}$  unless otherwise noted

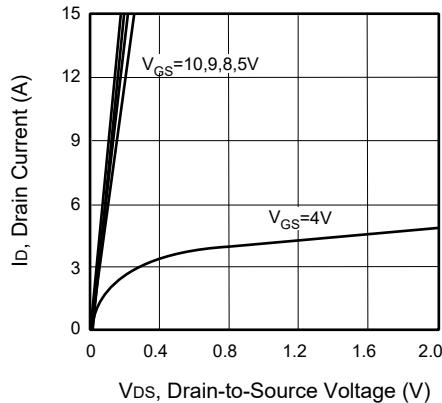
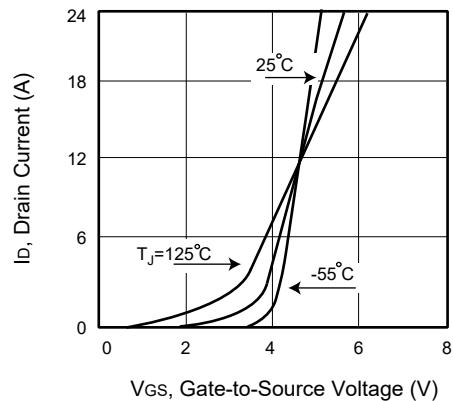
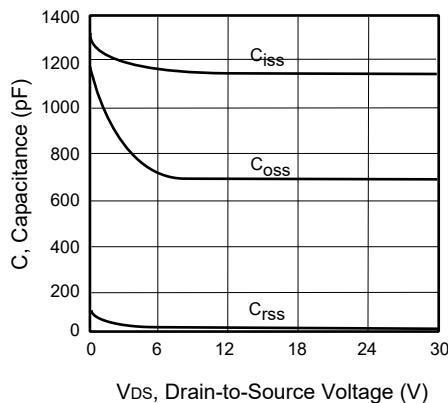
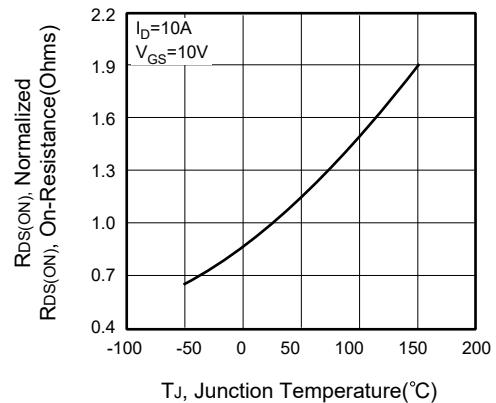
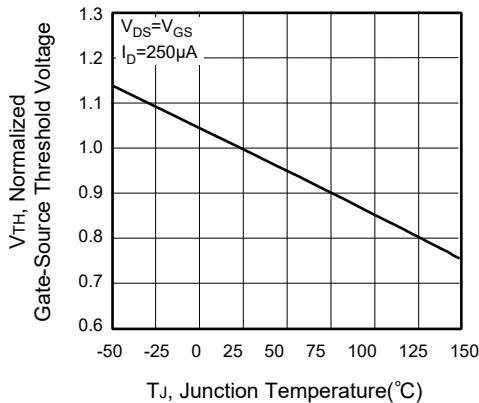
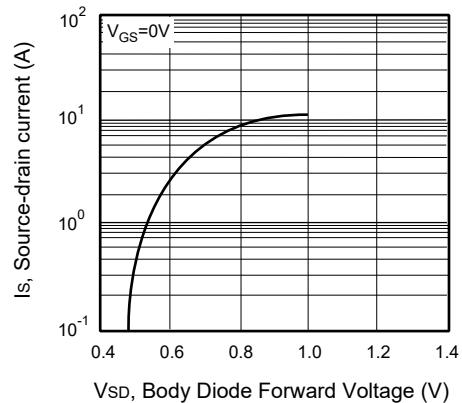
Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	100			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 100\text{V}, V_{\text{GS}} = 0\text{V}$		1		$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 20\text{V}, V_{\text{DS}} = 0\text{V}$		100		nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -20\text{V}, V_{\text{DS}} = 0\text{V}$		-100		nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2		4	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 10\text{A}$		10	12	$\text{m}\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 30\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		1135		pF
Output Capacitance	$C_{\text{oss}}$			700		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			5		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 50\text{V}, I_D = 1\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		23		ns
Turn-On Rise Time	$t_r$			6		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			43		ns
Turn-Off Fall Time	$t_f$			39		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 50\text{V}, I_D = 10\text{A}, V_{\text{GS}} = 10\text{V}$		21		nC
Gate-Source Charge	$Q_{\text{gs}}$			4		nC
Gate-Drain Charge	$Q_{\text{gd}}$			7		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_s$				3	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 10\text{A}$			1	V

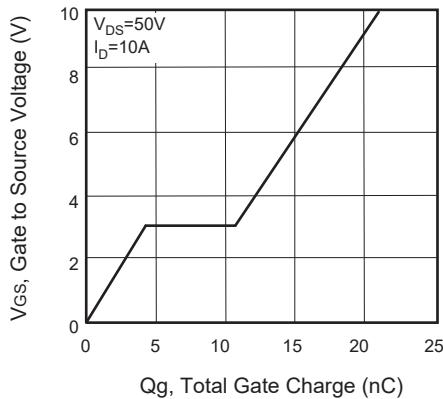
## Notes :

a.Repetitive Rating : Pulse width limited by maximum junction temperature.

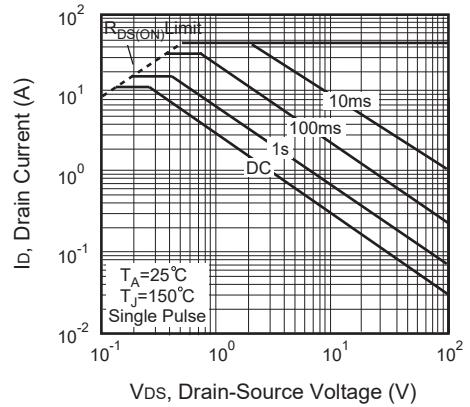
b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .

c.Guaranteed by design, not subject to production testing.

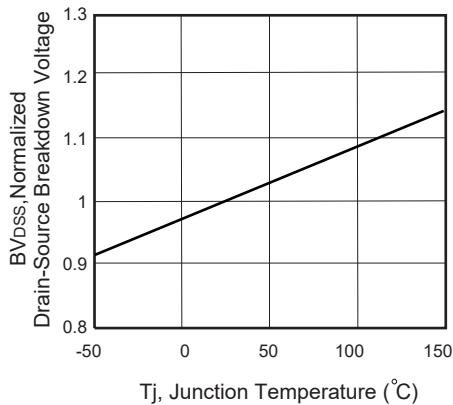
**Figure 1. Output Characteristics****Figure 2. Transfer Characteristics****Figure 3. Capacitance****Figure 4. On-Resistance Variation with Temperature****Figure 5. Gate Threshold Variation with Temperature****Figure 6. Body Diode Forward Voltage Variation with Source Current**



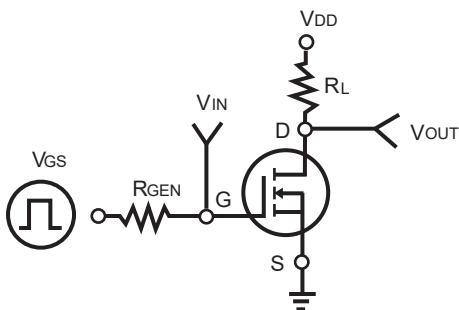
**Figure 7. Gate Charge**



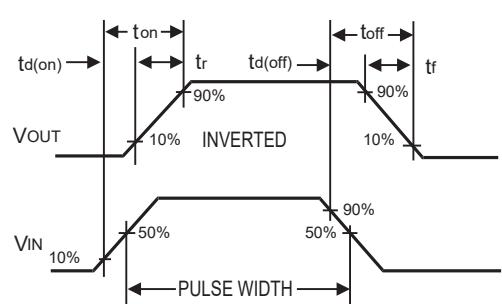
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Breakdown Voltage Variation VS Temperature**



**Figure 10. Switching Test Circuit**



**Figure 11. Switching Waveforms**

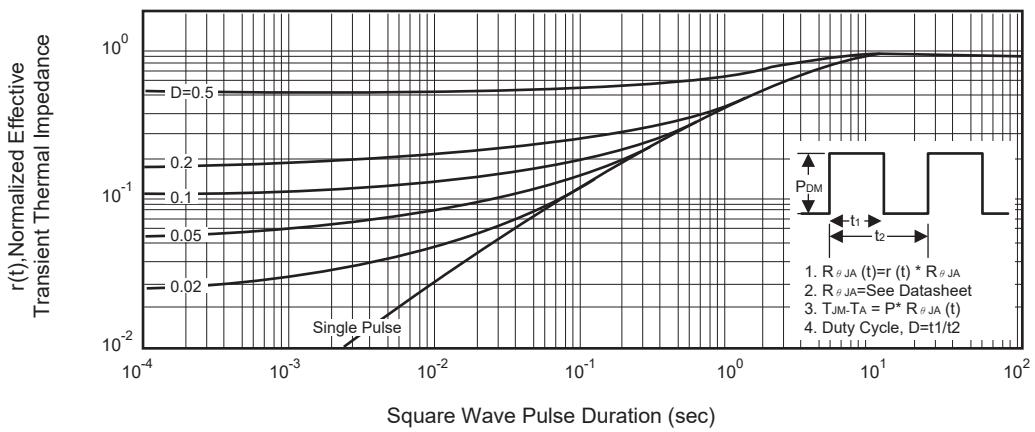


Figure 12. Normalized Thermal Transient Impedance Curve